## News Release Electronics for the Future

November 6, 2025



ROHM Co., Ltd.

## New Company Names Decided for Domestic Group Companies (Manufacturing-Related)

ROHM Co., Ltd. (hereinafter referred to as "ROHM") announced in October 2025 reorganization of its domestic manufacturing-related group companies—including the ROHM Shiga Plant and four other manufacturing-related companies—into two manufacturing companies, a wafer process manufacturing company (hereinafter "WP Company") and an assembly process manufacturing company (hereinafter "AP Company"), in order to strengthen ROHM Group's manufacturing capabilities and improve productivity. We are pleased to announce that the names of the new companies have now been decided.

\*Notice concerning company split associated with reorganization of the domestic group companies (Manufacturing-related)

WP Company: ROHM Device Manufacturing Co., Ltd. (RDM)
AP Company: ROHM Assembly Manufacturing Co., Ltd. (RAM)

Both companies will be responsible for the WP and AP manufacturing of semiconductors and other electronic components in Japan.

Additionally, ROHM Assembly Manufacturing will serve as the parent company overseeing overseas AP manufacturing subsidiaries, managing and operating their businesses.

This restructuring aims to establish a structure enabling speedy and optimal decision—making for the wafer process and assembly process, respectively. The sharing of technologies and know—how cultivated by each company will improve quality, while standardization and streamlining of business processes will enhance productivity, and also invigorate human resources through optimal staff allocation and a strengthened capability development system.

ROHM Group will strengthen its manufacturing capabilities that underpin its business operations, thereby improving its global competitiveness and building a business foundation resilient to market fluctuation.

## [Overview of the new company (projected)]

|                  | WP Company                            | AP Company                              |
|------------------|---------------------------------------|---|
| Company name     | ROHM Device Manufacturing Co., Ltd.   | ROHM Assembly Manufacturing Co., Ltd.   |
| Surviving        | ROHM Apollo Co., Ltd.                 | ROHM Wako Co., Ltd.                     |
| company          |                                       |   |
| Business         | Manufacturing of semiconductors and   | Manufacturing of semiconductors and     |
| description      | electronic components (WP)            | electronic components (AP)/ Overseeing  |
|                  |                                       | overseas AP manufacturing subsidiaries, |
|                  |                                       | managing and operating their businesses |
| Location         | 21 Saiin Mizosaki-cho, Ukyo-ku, Kyoto | 21 Saiin Mizosaki-cho, Ukyo-ku, Kyoto   |
| Name of          | Hidekazu Eguchi                       | Hirofumi Yoshioka                       |
| representative   |                                       |   |
| Capital          | 450 million yen                       | 450 million yen                         |
| ommencement      | April 1, 2026                         | April 1, 2026                           |
| date of business |                                       |   |